

### AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph numbered [0015] bridging pages 5 and 6, from line 17 on page 5 through line 8 on page 6, as follows:

[0015] As shown in FIG. 5, a plurality of the elements 20 to be bundled in close parallel spaced relation to each other are disposed in their desired relative positions within a body of uncured epoxy resin from which one of the holding discs 24 is separately formed within one of the seal rings 22 before assembly within a module 10. The epoxy resin in the uncured fluent state will fill all spaces between the axial end portions of the elements 20 to be bounded within the inner diameter of the annular seal ring 22. Positioning of the filter elements 20 during the latter described stage of the fabrication procedure, before molding of said one of the holding discs 24, is established by clamping between fixedly spaced rigid plates 30 and 32 on which resilient material layers 34 and 36 are respectively disposed. To facilitate molding, a thin mold release film 38 is placed on the resilient layer 34 underlying the lower ends of the elements 20 within the uncured body of epoxy resin retained within the seal ring 22 24 under pressure as denoted by arrow 40 and a clamping pressure on the plate 32 as denoted by arrow 42. The thickness of the holding discs 24 is determined by the height of the seal ring 22. When one of such discs 24 is so formed upon full curing of the epoxy resin after 24 hours for example, the element bundle as shown in FIG. 5 is then rotated 180° and the same fabrication procedure is repeated to form another holding disc 24 at the other ends of the elements 20, not shown in FIG. 5, to complete bundling of the elements before transfer to the module 10 for assembly therein.